

Title (en)
LOW-RESISTANCE VOID-FREE CONTACTS FOR EEPROM DEVICES

Title (de)
LÜCKENLOSE KONTAKTE MIT GERINGEM WIDERSTAND FÜR EEPROM-GERÄTE

Title (fr)
CONTACTS SANS VIDE À FAIBLE RÉSISTANCE

Publication
EP 1958252 A2 20080820 (EN)

Application
EP 06848514 A 20061129

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Abstract (en)
[origin: WO2007067860A2] A plug is formed by depositing a first material to partially fill an opening, leaving an unfilled portion with a lower aspect ratio than the original opening. A second material is then deposited to fill the remaining portion of the opening. The first material has good filling characteristics but has higher resistivity than the second material. The second material has low resistivity to give the plug low resistance.

IPC 8 full level
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CPC (source: EP)
H01L 21/76877 (2013.01); **H10B 41/30** (2023.02); **H10B 41/35** (2023.02); **H10B 69/00** (2023.02); **G11C 16/0483** (2013.01); **H10B 43/30** (2023.02)

Citation (search report)
See references of WO 2007067860A2

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